TECHNICAL INFORMATION

Super Fine Particle
SOLDER PASTE
SE(S)70 – A310

[Content]

KOKI COMPANY LIMITED

1. FEATURES

1) Ensures **OUTSTANDING** continual **PRINTABILITY** with super fine pattern applications (0.5mm pitch CSP, 0402 components) and long stencil idle time. **PERFECT MELTING** and wetting at super fine pitch (<0.4mm pitch) and micro components (<0.3mm dia CSP, 0603 chip).

2) Designed to cope with super fine pattern application, e.g. <0.2mm diameter CSP pattern, and ensures **PERFRECT COALESCENCE** and **WETTING**.

2. SPECIFICATION

1) Alloy

Item	Unit	**SE70-A310**	**SS70-A310**	Remarks
Composition	%	Sn63, Pb37	Sn62, Pb36, Ag2	JIS S grade
Shape	--	Spherical		Microscope×50
Particle size	μm	10 - 25		

2) Flux

Halogen content		%	0.2	Potentiometer
SIR*[1]	Initial value	Ω	$> 1\times10^{12}$	JIS comb type electrode type Ⅱ
	After humidification		$> 1\times10^{11}$	
Aqueous solution resistivity*[2]		Ω cm	$> 1\times10^{4}$	Conductivity
Flux type		–	ROL1	ANSI/J-STD-004

3) Solder paste

Flux content	%	12	By weight
Viscosity*[3]	Pa.s	130±20	Malcom PCU-2
Copper plate corrosion*[4]	--	Passed	--
Solder spreadability	%	90	Copper plate
Tack time	hour	> 20	Malcom FG-1
Shelf life	month	3	Below 10°C

1. SIR ..... 40°C×90%RH×96Hr
2. Aqueous solution resistivity..... In accordance with MIL specifications.
3. Viscosity ..... Malcom spiral type viscometer, PCU-2 at 25°C 10rpm
4. Copper plate corrosion..... In accordance with JIS

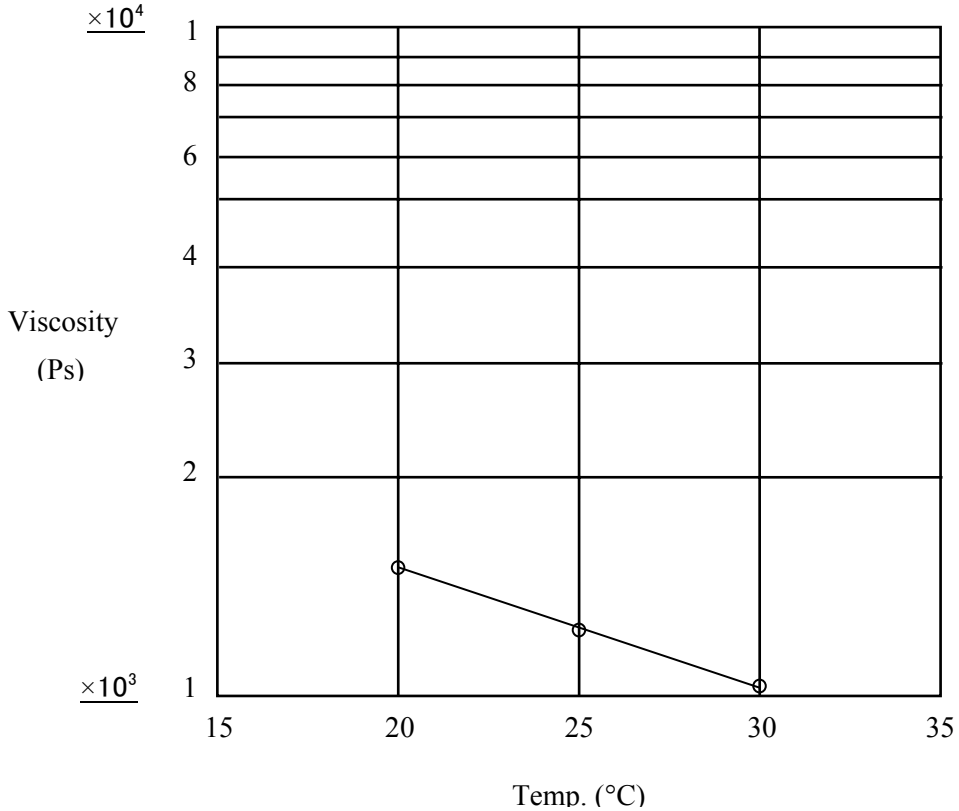
3. TEMPERATURE - VISCOSITY CURVE

• Test method

Equipment : Malcom viscometer PCU-2
Rotation of spindle : 10 r.p.m.
Measuring time : 5 min.

• Test result

Measuring temp. (°C)	Viscosity (Ps)
20	1510
25	1290
30	1020



4. TACKINESS

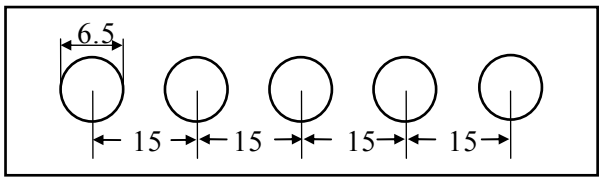
• Test method

Print the solder paste on the alumina plate with a 0.2mm thick stencil that has five 6.5mm dia. holes, to obtain test piece.

Press a flat tip of a cylindrical probe of Malcom Solder Checker FG-1 on to the printed solder paste with the pressure of 50gs for 0.2mm sec. and pull it back up at the speed of 10mm/sec. to measure maximum tensile strength needed to separate the probe from the paste.

Evaluate tackiness of the solder paste from obtained tack force and time after printing.

*Ambient condition : 25°C, 50±10%RH

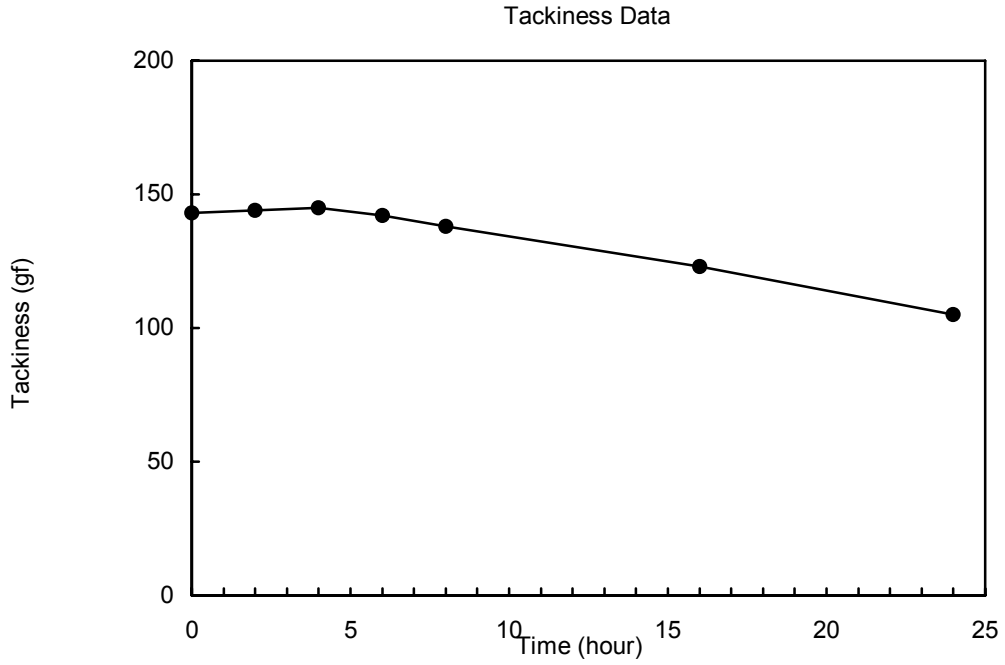


*Unit : mm

Stencil used

Time (hour)	0	2	4	6	8	16	24
Tack force (gf)	143	144	145	142	138	123	105

*Unit : (gf) Average of n = 5



5. SLUMP

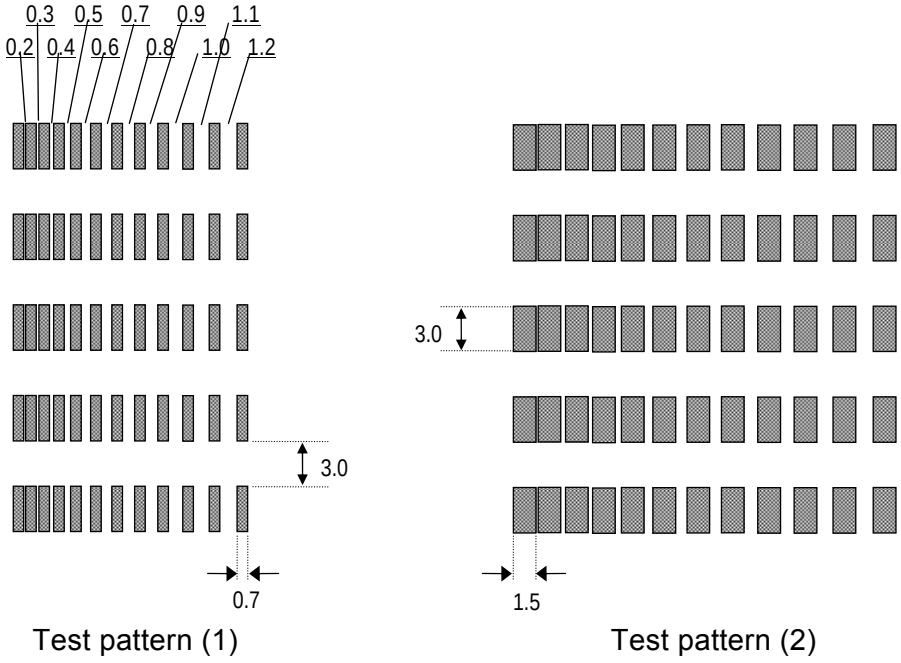
• Test method

Using 0.2mm thick stainless steel stencil with two patterns of apertures, (1)3.0mm×0.7mm, (2)3.0mm×1.5mm arranged as grids with the spacing between the apertures varying from 0.2mm to 1.2mm in steps of 0.1mm, print the solder paste on 1.6mm thick copper clad laminate plate to obtain test pieces.

(1) Observe the slump behavior after leaving the test pieces at room temperature for 1 hour.

(2) Observe the minimum spacing across which the paste has no merged after storing the test pieces at room temperature for 1 hour, and heating it for 20 minutes at 100°C in the thermostatic oven.

(3) Observe the minimum spacing across which the paste has not merged after storing the test pieces at room temperature for 1 hour, and heating it for 5 minutes at 150°C in the thermostatic oven.



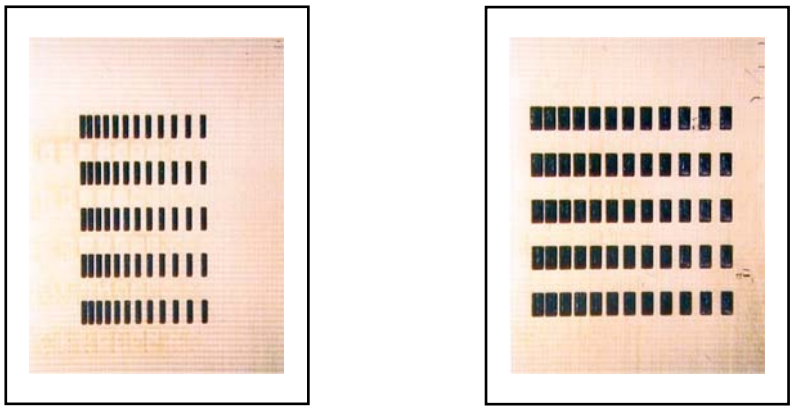
Test pattern (1) Test pattern (2)

• Test result

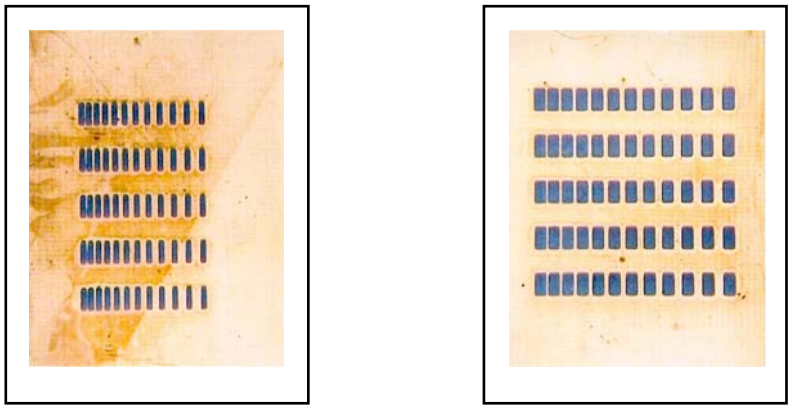
n	Stored at room temperature for 1 hour		
	Room temp.	100°C×20min.	150°C×5min.
(1)	0.2	0.3	0.4
(2)	0.2	0.3	0.4

*Store at room temperature for 1 hour.

[Room temperature (no heating)]



[150°C × 5min.]



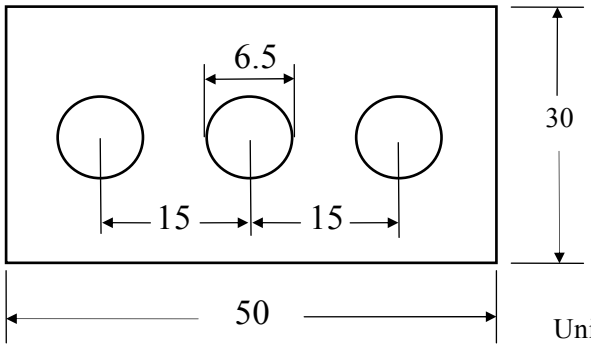
6. SOLDER BALL

• Test method

Prepare two test pieces by printing the paste on each alumina plate (50×50×0.8tmm) with a 0.2mm thick stencil provided with three 6.5mm diameter apertures with a distance between centers of 15mm.

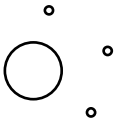
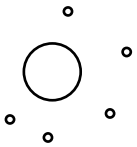
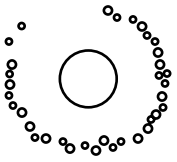
Reflow one of them in 1 hour after printing and the other after storing it at 25±2°C60±20%RH for 24 hours, on a hot plate at 250°C. Remove the test pieces from the hot plate after 5 seconds since the solder paste melted completely and cool them down to room temperature.

Inspect the degree of reflowing referring to 'Solder balling evaluation standard' using the×10 magnifying glass.



Stencil used.

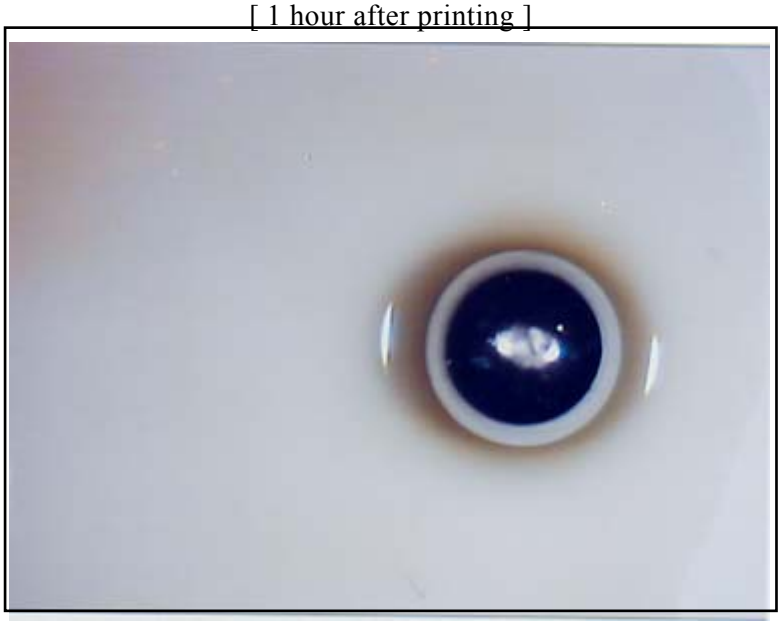
• Solder balling evaluation standard

Category	Status of coalescence of solder	Illustration (ex.)
1	The molten solder from the paste has melted in to one solder ball.	
2	The molten solder from the paste has melted into one large solder ball with no more than three isolated small solder balls with diameter less than 75μm.	
3	The molten solder from the paste has melted into one large solder ball surrounded by more than three solder balls with diameters less than 75μm which do not form a semi-continuous halo.	
4	The molten solder from the paste has melted into one ball accompanied by a large number of smaller solder balls which may form a semi-continuous halo, or has melted to form a number of similarly sized balls.	

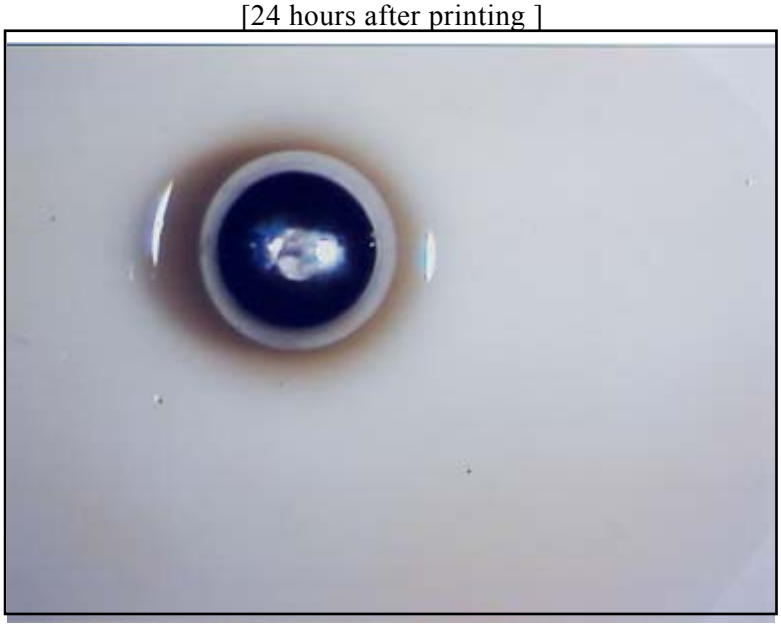
• Test result

Test piece	1 hour after print	24 hours after print
a	Category 3	Category 3
b	3	3
c	3	2

[1 hour after printing]



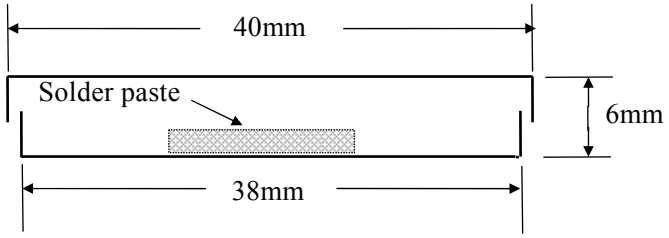
[24 hours after printing]



7. COPPER PLATE CORROSION

• Test method

Prepare 6 pcs. of phosphorus deoxidized copper plate of 50×50×0.5tmm in size (JIS-H-3100). Bend 3 of them at right angle at 5mm (copper plate A), and the rest at 6mm (copper plate B) from the both edges to form three open ended boxes.



After removing grease from the both copper plate A and B with acetone, soak them in 5% sulfuric acid for 1 minute and in ammonium persulfate solution (solution which contains 25% of ammonium persulfate in 0.5% of sulfuric acid) in 1 minute to etch the surface uniformly. After washing them with running water , soak in 5% sulfuric acid for 1 minute and rinse thoroughly with running tap water and demineralized water. Then, finally, rinse them with acetone and dry.

Obtain test pieces by printing solder paste on the copper plate B with a 0.2mm thick stencil provided with 6.5mm diameter aperture.

Place all three copper plate A over the copper plate B and lower each box in a horizontal position on to the surface of the solder bath at the temperature of 235±2°C and maintain the test pieces in this position for 5 seconds.

Remove each test piece from the solder bath and allow it to cool in a horizontal position down to room temperature. Place all three boxes in the thermohygrostat under the condition of 40±2°C, 90~95%RH for 72 hours.

Remove the boxes from the thermohygrostat and inspect the inside surfaces of the boxes (including the lid) for possible corrosion.

• Test result

n	Copper plate A	Copper plate B
1	No corrosion	No corrosion
2	No corrosion	No corrosion
3	No corrosion	No corrosion

8. SURFACE INSULATION RESISTANCE

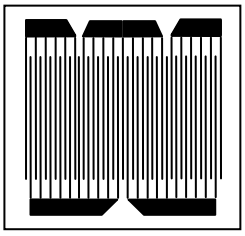
• Print the solder paste with a 0.1mm thick stencil on comb type electrode type-IIspecified in JIS-Z-3197 6.8. and reflow them to obtain test piece.

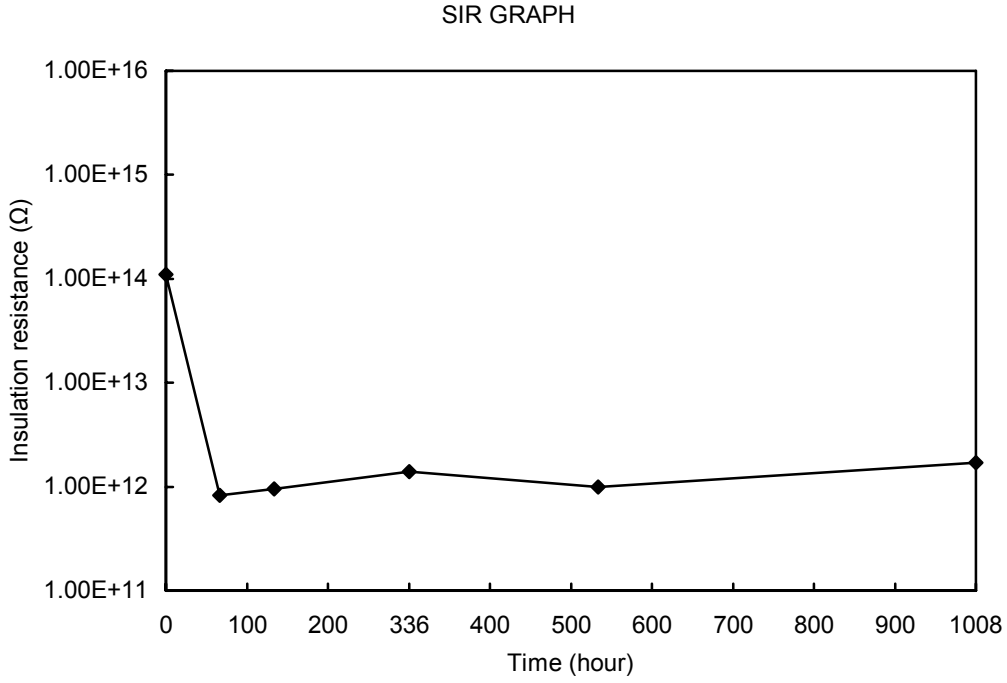
Put the test piece in a thermohygrostat under the conditions of 85±2°C and 85±2%RH.

Measure the insulation resistance at every specific time taking the test pieces out of the thermohygrostat. DC100V for the measurement.

• Test result

Time (hour)	S.I.R. Value (Ω)
Initial value	2.0×10^{14}
96	5.0×10^{11}
168	6.5×10^{11}
336	7.8×10^{11}
504	9.3×10^{11}
1008	1.2×10^{12}

Comb type electrode Type - II	
	
Width of conductor	0.318
Conductor spacing	0.318
Overlap length	15.75



9. VOLTAGE APPLIED SIR

(Electromigration Test)

• Test method

Print the solder paste with a 0.1mm thick stencil on comb type electrode Type-II specified in JIS-Z-3196 6.8. and reflow them to obtain test pieces.

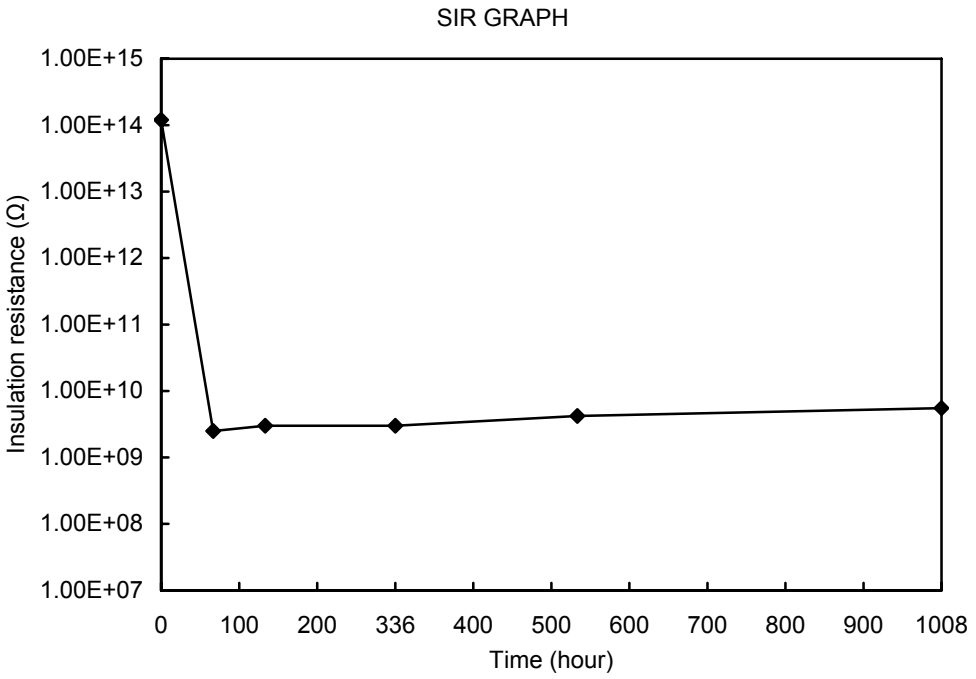
Put the test pieces in a thermogygrostat under the conditions of 85±2°C and 85±2%RH.

Measure the insulation resistance at every specific time keeping the test pieces in the thermohygrostat and apply DC50V. Apply 100V for the measurement.

• Test result

Time (hour)	Place measured	Average (Ω)
Initial value	Out thermohygrostat	1.2×10^{14}
96	In thermohygrostat	2.5×10^{9}
168	In thermohygrostat	3.0×10^{9}
336	In thermohygrostat	3.0×10^{9}
504	In thermohygrostat	4.2×10^{9}
1008	In thermohygrostat	5.5×10^{9}

☆ There was no evidence of electromigration.



10. USE OF KOKI SOLDER PASTE

In order to make the paste use of KOKI SOLDER PASTE, please refer to the following guideline carefully before use.

1. Preparation for printing

1) Temperature

After taking a solder paste out of the refrigerator, in which the temperature is controlled to be below 10°C, wait the paste temperature come back to a room temperature

*Caution : Do not open the jar while it is cold, or it causes condensation of moisture on the paste, and could be a cause of poor performance, such as increase of viscosity, solder balling and etc.

Do not heat the paste.

2) Stirring

By using a stainless steel or chemically resistive plastic spatula, stir up the paste before use.

It is recommended to stir it for at least 1~2 min. to obtain uniform and stable viscosity.

*Caution : When an automatic stirring equipment is used, do not stir the paste longer than 4 min.

2. Printing

1) Recommended printing parameters

(1) Squeegee

1. Kind : Flat
2. Material : Rubber or metal blade
3. Angle : 60~70°
4. Pressure : Lowest
5. Squeegee speed : 10~50mm/sec.

(2) Stencil

1. Stickiness : 100~50μm for 0.65~0.3mm pitch pattern
2. Snap-off distance : 0~0.5mm

*Although on-contact (0 snap-off) is normally recommendable for fine pitch printing, if a printing equipment is not provided with a stencil separation speed control system, proper snap-off distance shall be provided to ensure smooth and gradual separation of the stencil from the substrate for good solder paste deposits.

3. Fixing method of substrate : It is recommended to have a fixture or vacuum system to hold the substrate in position during printing to prevent movement of PC board and to have a good separation from the stencil.
4. It is strongly recommended to set stencil separation speed as slow as possible.

(3)Ambiance

1. Temperature : 22 - 25°C
2. Humidity : 40~60%RH
3. Wind : Wind badly affects stencil life and tack performance of solder pastes.

*Caution : When local air conditioner is equipped, make sure it is not enhancing drying out of solder paste.

(4) Printing

1. Initial quantity of solder paste to put on the stencil shall be decided according to the size of the stencil (PC board).

   Ex. Size of PC board A5 - approx. 200gs
   B5 - 300gs
   A4 - 400gs

   *In order to ensure good rolling of the paste across the stencil and easy separation from squeegees, a certain amount of solder paste must be required through out the printing process.

2. Add the paste to replenish only the consumed amount.

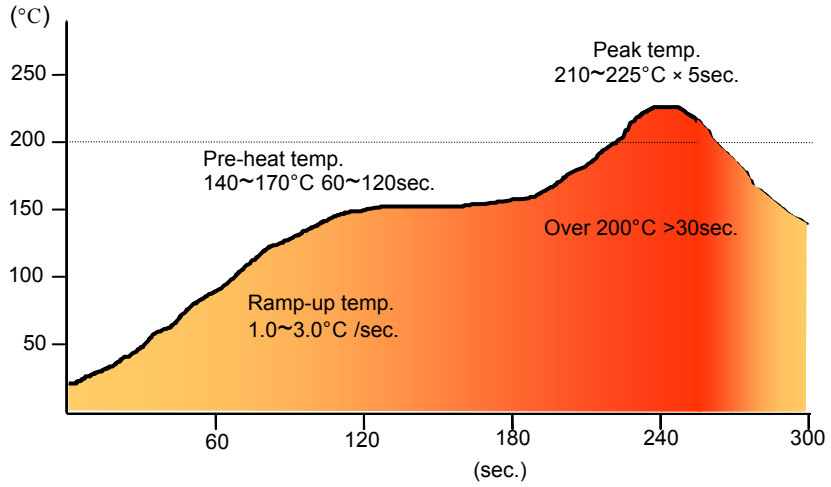
   *Minimize the amount of paste left on the stencil as the degradation gets accelerated once it is processed on the stencil.

3. Every after certain times of continuous printing, thoroughly clean the bottom side or both the top and bottom side of the stencil.

4. Clean both the top and bottom side of the stencil before every break.

5. Do not return the used paste into the original jar to prevent mixture and contamination of the fresh paste, but put it in a separate container for reuse, if necessary.

3. Reflowing



4. Storage

Store in a refrigerator at 10°C.

DO NOT FREEZE!

5. Shelf life

1) 5 ~ 10°C : 3 months from manufacturing date
2) At 20°C : 1 month from manufacturing date
3) At 30°C : 1 month from manufacturing date

* Manufacturing date can be obtained from the lot number

ex. **Lot No. 7 07 21 2**

No. of lot : 2nd
Date : 21st
Month : July
Year : 2007